

# FOX ULTRA SMD Pick & Place System

Version 5.2 / December 2025

## Specifications

		FOX <sup>1</sup>		FOX <sup>2</sup>		FOX <sup>4</sup>	
		Stand Alone	In Line	Stand Alone	In Line	Stand Alone	In Line
Productivity	Optimum placement speed <sup>(1)</sup>	Chip 9'100 cph		Chip 17'500 cph		Chip 31'000 cph	
	Speed (IPC 9850) <sup>(1)</sup>	Chip 7'300 cph QFP 6'700 cph		Chip 13'600 cph QFP 6'700 cph		Chip 20'500 cph QFP 9'600 cph	
	Speed (IPC 9850A) <sup>(1)</sup>	Chip 7'000 cph QFP 5'300 cph		Chip 12'700 cph QFP 5'300 cph		Chip 18'500 cph QFP 6'700 cph	
	Jet speed solder paste up to Shockwave valve	Optimum <sup>(2)</sup> Dot matrix <sup>(3)</sup> Application average <sup>(4)</sup>		1'100'000 dots/h 665'000 dots/h 350'000 dots/h		-	
	Jet speed glue up to Piezo valve	Optimum <sup>(5)</sup> Dot matrix Jet-on-the-Fly <sup>(6)</sup> Dot matrix Stop 'n Jet <sup>(6)</sup>		2'000'000 dots/h 780'000 dots/h 177'000 dots/h		-	
	Dispensing speed up to <sup>(6)</sup>	Time/pressure valve Archimedean screw valve Volume dispenser valve		38'000 dots/h 30'000 dots/h 26'000 dots/h		-	
	Job changeover time	< 1 min (loading job, adjust conveyor/table, restart production)					
Feeder <sup>(7)</sup>	Feeder system	EVO and hyQ (intelligent single feeder) CLM (intelligent cassette feeder) <sup>(8)</sup> <i><sup>(9)</sup> Restrictions on FOX<sup>4</sup> with CLM racks on front, see System Description</i>					
	Feeder capacity (8mm tape)	180	120	180	120	180 / 200 <sup>(10)</sup>   120 / 140 <sup>(11)</sup> <i><sup>(12)</sup> with optional Extended Rack, pick position cannot be taught with top camera</i>	
Components	Component size range	008004 (imp.) – 109 x 87 mm		Complete range, see constraints below			
		Constraints:		<ul style="list-style-type: none"> <li>0201 (imp.) – 40 x 40 mm incl. leads → Standard</li> <li>Up to 87 x 35 mm incl. leads → With optional MFOV<sup>(13)</sup> software license</li> <li>Up to 109 x 87 mm incl. leads → With opt. MFOV license and Vision Box<sup>(14)</sup></li> <li>01005 (imp.) → With opt. Nozzle 0 and EVO feeder type</li> <li>008004 (imp.) / 0201 (m) <sup>(8)</sup> → With opt. Nozzle 0 and EVO feeder type</li> </ul>			
				<sup>(15)</sup> Multi Field of View			
				<sup>(16)</sup> Requires space up to 22 hyQ/EVO - 30 CLM Feeder lanes, front side mounting only (see System Description)			
	Mass moment of inertia	200 g x cm <sup>2</sup>					
	Min. lead pitch	0.3 mm (12mil)					
	Min. ball diameter / pitch	0.2 mm					
	Min. component height	> 0.0 mm					
	Max. component height	Standard: 18 mm / On request other heights					
	Process height	± 18 mm (0.71") from zero height					
Accuracy	Linear encoder resolution XY	0.2 µm					
	Rotation axis resolution	0.007°					
	Overall placement accuracy XY chip	± 40 µm (3σ) <sup>(9)</sup>					
	Overall placement accuracy XY QFP	± 30 µm (3σ) <sup>(9)</sup>					
PCB	Min. PCB dimensions	20 x 20 mm (0.8 x 0.8")	50 x 50mm (2 x 2")	20 x 20 mm (0.8 x 0.8")	50 x 50mm (2 x 2")	20 x 20 mm (0.8 x 0.8")	50 x 50mm (2 x 2")
	Max. PCB dimensions	406 x 305 mm (16 x 12")					
	PCB thickness	0.5-3.5 mm (0.02 - 0.13")	0.5-5.0 mm (0.02 - 0.2")	0.5-3.5 mm (0.02 - 0.13")	0.5-5.0 mm (0.02 - 0.2")	0.5-3.5 mm (0.02 - 0.13")	0.5-5.0 mm (0.02 - 0.2")
	PCB edge clearance	3.0-5.0 mm (0.11 - 0.2") <i>(varies with PCB thickness)</i>	T: 3.0 mm (0.11") B: 5.0 mm (0.2")	3.0-5.0 mm (0.11 - 0.2") <i>(varies with PCB thickness)</i>	T: 3.0 mm (0.11") B: 5.0 mm (0.2")	3.0-5.0 mm (0.11 - 0.2") <i>(varies with PCB thickness)</i>	T: 3.0 mm (0.11") B: 5.0 mm (0.2")
	Max. board weight	-	4 kg (8.8 lb)	-	4 kg (8.8 lb)	-	4 kg (8.8 lb)
	Conveyor height	-	SMEMA 940 – 965 mm	-	SMEMA 940 – 965 mm	-	SMEMA 940 – 965 mm
	Clearance below PCB	40 mm (1.57")	27 mm (1.1")	40 mm (1.57")	27 mm (1.1")	40 mm (1.57")	27 mm (1.1")



**Configuration**

		FOX <sup>1</sup>	FOX <sup>2</sup>	FOX <sup>4</sup>
Machine base	Pick & Place head with 1 spindle, optional 1x dispensing axis	●		
	Pick & Place head with 2 spindles, optional 1x dispensing axis		●	
	Pick & Place head with 4 spindles			●
	Dual bottom camera system			●
	Stand alone type (PCB table, magnetic PCB holder, support pins)	○	○	○
	In line type (conveyor 3 stage, support pins, manual width adjustment)	○	○	○
	Dispensing preparation kit (dot plate, purge and z-height calibration station)	○	○	
	Interior lighting LED	●	●	●
	Signal tower (3 color)	●	●	●
PCB Handling	IPC-HERMES-9852, SMEMA interface	●	●	●
	Inline systems: Conveyor direction L/R, R/L, batch mode R/R, L/L	●	●	●
	Inline systems: Automatic conveyor width adjustment	○	○	○
	Inline systems: Conveyor extensions	○	○	○
	Inline systems: PCB inspection station on conveyor	○	○	○
Control and software	ePlace P&P software (En, De, Fr, Ru, Pl, Zh, Es, Cs, Ja)	●	●	●
	Machine PC with Windows 11 OS and 21.5" touch screen	●	●	●
	Technical support software	●	●	●
Alignment systems	Cognex SMD4 PatMax vision license (fiducials, chip, QFP, asymm. BGA and leads)	●	●	●
	Red and blue color illumination for top camera	●	●	●
	Multi Field of View license (MFOV)	○	○	○
	Vision box for bigger components	○	○	○
	Laser height measurement	○	○	○
Dispensing valves (Cartridge sizes)	Piezo jet valve (5, 10, 30 cm <sup>3</sup> )	○	○	
	Shockwave jet valve (5, 10, 30 cm <sup>3</sup> )	○	○	
	Time/pressure valve (5, 10, 30 cm <sup>3</sup> )	○	○	
	Archimedean screw valve (5, 10, 30 cm <sup>3</sup> )	○	○	
	Volume dispenser valve (10, 30, 55 cm <sup>3</sup> )	○	○	
	Cartridge level control	○	○	
	Dispenser needle heating	○	○	
	Various (extract)	Standard user level management	●	●
Bad mark sensing with vision	●	●	●	
Universal CAD conversion	●	●	●	
Automatic pick position correction and feeder advance optimization	●	●	●	
Automatic placement constraints	●	●	●	
Basic calibration set P&P	●	●	●	
Maintenance kit	●	●	●	
Process Improvement Tool P&P (PIT1 – 3 pictures)	●	●	●	
Key Performance Indicator (KPI with SEMI E10 standard)	○	○	○	
Barcode reading over top camera	○	○	○	
Disp. Process Control Adjustment & Stabilization (PCAS)	○	○		
Second touch screen for machine backside	○	○	○	
CVU (Component Verification Unit)	○	○	○	
Tray slider (space for two additional JEDEC trays) Reduces max. PCB dimension in Y from 305 to 260 mm (* Picking-area restrictions, see System Description)	○(*)	○	○	
Tray changer (space for up to 18 JEDEC trays)	○	○	○	
Extended feeder rack (additional feeder lanes)			○	
Recipe import in ePlace	○	○	○	
Communication interfaces: IPC-CFX, HERMES, ITAC, SECS/GEM, OIC, EEIP etc.	○	○	○	
Integrated inspection system for pick & place and dispensing (SW-I25)	○	○	○	
Jet on the fly - Extended Speed Performance (SW-ESP, see Application Matrix)	○	○	○	

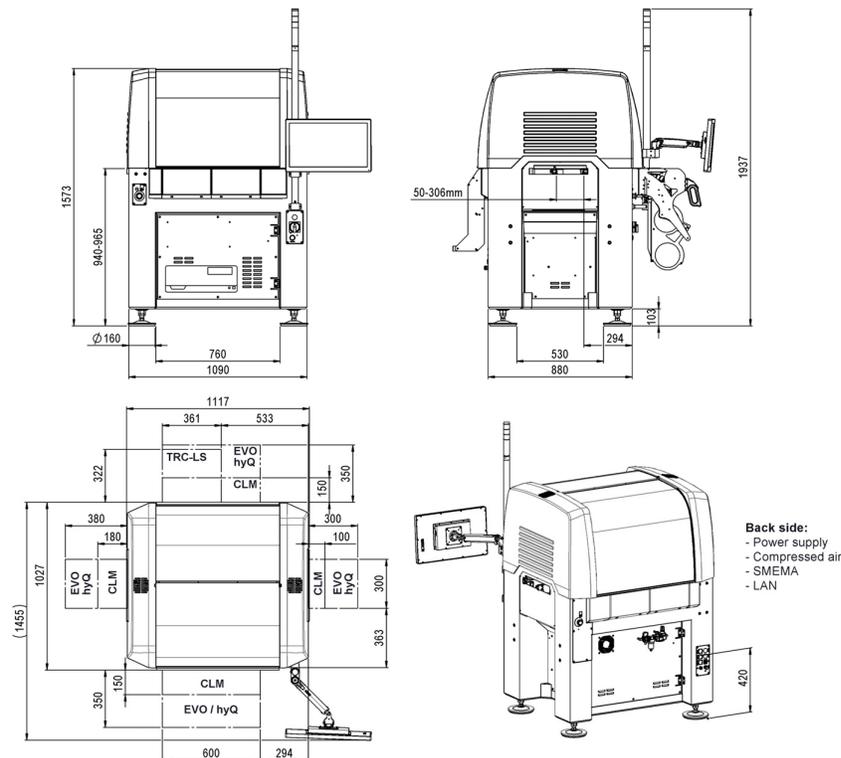
● standard feature      ○ optional feature



### Machine Dimensions, Packaging and Supplies

Machine dimensions	Footprint without hood (L x W)	880 x 1090 mm (35 x 43")
	Footprint with hood (L x W)	1027 x 1117 mm (40 x 44")
	Operating floor space (L x W)	1865 x 1797 mm (73 x 71")
	Height (without / with light tower)	1578 mm (62") / 1939 mm (76")
	Approx. machine weight (without / with feeder)	875 kg (1929 lb) / 1020 kg (2249 lb)
	Approx. floor loading (without / with feeder)	912 kg/m <sup>2</sup> (1.3 lb/sq.in) / 1065 kg/m <sup>2</sup> (1.51 lb/sq.in)
	Packaging weight	70 kg (154 lb)
Supplies	Electrical	230V / 50Hz or 120V / 60Hz (with optional transformer)
	Power consumption (average / peak)	0.75 kW / 1.7 kW
	Entry fuse	13A / 230V
	Min. wire cross section	1.5 mm <sup>2</sup>
	Electrical connector	230V, CEE-16, 16A, 230V, 3P L+N+PE 6h, blue color, cable length 2.7 m 120V, CEE-16, 16A, 120V, 3P L+N+PE 4h, yellow color, cable length 2.7 m
	Compressed air	6 - 7 bar (87 - 102 psi), clean and filtered, dry, ISO 8573-1: class 3 (max. part diameter 5µm, dew point < -20°C, oil ≤ 1 mg/m <sup>3</sup> )
	Air consumption	max. 60 NI/min (2.1 cfm) With dispensing option vacuum cleaning station max. 90 NI/min (3.2 cfm)
Air connection	Push-in connector for outer hose Ø8 mm	
Environment	Performance temperature range / humidity	22 - 24°C / 50 - 70% RH
	Operational temperature range / humidity	15 - 30°C / 30 - 70% RH (non condensing)
	Noise level	max. 75 dB (A)

### Dimension Drawings



- 1) Values reached using EVO and hyQ feeder type only.
- 2) Maximum valve frequency, using settings from solder paste Application Matrix with Jet-on-the-Fly capability (req. SW-ESP license)
- 3) Dot matrix 33x33 with pitch 1.0 x 1.0 mm, using settings from solder paste Application Matrix with Jet-on-the-Fly capability (req. SW-ESP license)
- 4) Average of 17x different industrial PCBs, using settings from solder paste Application Matrix with Jet-on-the-Fly capability (req. SW-ESP license)
- 5) Maximum valve frequency
- 6) Dot matrix 33 x 33 with pitch 0.8 x 0.8 mm, dot size 0.5mm, medium Loctite 3621
- 7) Some feeder type «CSM» are also compatible. See System Description for possibilities and details.
- 8) Under conditions specified by Essemtec
- 9) Used speed mode "very accurate", up to 3 different speed modes available. Measured with chip 0402 and glass QFP100. Only applicable at zero height and within performance temperature / humidity range.

For more information ask for the FOX ULTRA System Description and Product Notes.

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